

INTERNATIONAL ELECTROTECHNICAL COMMISSION
COMMISSION ÉLECTROTECHNIQUE INTERNATIONALE

IEC 60068-2-69
Edition 3.0 2017-03

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ENVIRONMENTAL TESTING –

**Part 1: 2-69: Tests – Test Te/Tc: Solderability
testing of electronic components and
printed boards by the wetting balance
(force measurement)**

ESSAIS D'ENVIRONNEMENT –

**Partie 2-69: Essais – Essai Te/Tc: Essai de
brasabilité des composants électroniques et
cartes imprimées par la méthode de la balance
de mouillage (mesure de la force)**

CORRIGENDUM 1

Corrections to the French version appear after the English text.

Les corrections à la version française sont données après le texte anglais.

7.1.4 Solder contamination control

Replace Table 2 with the following new table:

Table 2 – Maximum limits of solder bath contaminants

Contaminant	Maximum mass fraction contaminant limit	
	SnPb alloys ^{a, b} %	Lead-free alloys ^{c, d} %
Copper	0,300	1,100
Gold	0,200	0,200
Cadmium	0,005	0,005
Zinc	0,005	0,005
Aluminium	0,006	0,006
Antimony	0,500	0,200
Iron	0,020	0,020
Arsenic	0,030	0,030
Bismuth	0,250	0,250
Silver	0,100	4,000
Nickel	0,010	0,050
Lead	N/A	0,100
^a The tin content of the solder shall be maintained within $\pm 1,5$ % of the nominal alloy being used. Tin content shall be tested at the same frequency as testing for copper/gold contamination. The balance of the bath shall be lead and/or the items listed above. ^b The total of copper, gold, cadmium, zinc, and aluminium contaminants shall not exceed 0,4 %. Not applicable to lead-free alloys. ^c The tin content of the solder shall be maintained within ± 1 % of the nominal alloy being used. Tin content shall be tested at the same frequency as testing for copper/silver concentration. The balance of the bath shall be the items listed above. ^d Maximum contamination limits are applicable for Sn96,5Ag3Cu,5. Other lead-free solder alloy contamination limits may be used upon agreement between user and vendor.		

8.2.2 Solder bath wetting balance procedure

Replace the 3rd paragraph to Table 5 with the following new paragraph:

The recommended immersion speed for all components is between 1 mm/s and 5 mm/s, except for leaded non-SMD where between 5 mm/s and 20 mm/s is recommended.

8.2.4.2 Procedure

In the 1st paragraph, replace "7.2.3" with "7.2.1".

10 Information to be given in the relevant specification

In the list item e), replace "8.2.2" with "8.2.3".

In the list item l), replace with the following text and replace "9.2" with "8.2.2, 8.2.3":

Areas to be visually examined for wetting and de-wetting